Product Information Sheet

EPO-TEK® EK1000-1

Date:	March 2021	**Recommended Cure: 150°C/1 Hour plus 200°C/1 Hour (post-cure)**	
Rev:	VII		
No. of Components:	Single	Minimum Alternative Cure(s):	
Mix Ratio by Weight:	N/A	*May not achieve performance properties listed below*	
Specific Gravity:	3.76	200°C / 30 Minutes	
Pot Life:	2 Weeks **Dry Time:** < 7 Days	150°C / 1 Hour	
Shelf Life- Bulk:	One year at -40°C		

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: EPO-TEK® EK1000-1 is a single component, longer dry time version of EPO-TEK® EK1000 designed for applications requiring longer working time.

Typical Properties: Cure condition: varies as required Different batches, conditions & applications yield differing results.
Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Silver		
* Consistency:	Smooth thixotropic paste		
* Viscosity (23°C) @ 10 rpm:	13,000-21,000	cPs	
Thixotropic Index:	3.7		
* Glass Transition Temp:	≥ 80	°C (Dynamic Cure: 20-300°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
Below Tg:	41	x 10^{-6} in/in°C	
Above Tg:	162	x 10^{-6} in/in°C	
Shore D Hardness:	65		
Lap Shear @ 23°C:		psi	
Die Shear @ 23°C:	≥ 10	Kg 3,556 psi	
Degradation Temp:	375	°C	
Weight Loss:			
@ 200°C:	0.04	%	
@ 250°C:	0.15	%	
@ 300°C:	0.50	%	
Suggested Operating Temperature:	< 300	°C (Intermittent)	
Storage Modulus:	609,195	psi	
Ion Content:	Cl^-: < 200 ppm	Na^+: < 50 ppm	
	NH_4^+: > 5 ppm	K^+: < 50 ppm	
* Particle Size:	≤ 45	microns	

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity (150°C/1 Hour):	12.1	W/mK
Thermal Conductivity(150°C/1 Hour + 200°C/1 Hour):	22.7	W/mK
* Volume Resistivity @ 23°C:	≤ 0.0007	Ohm-cm

EPOXY TECHNOLOGY, INC.
14 FORTUNE DRIVE, BILLERICA, MA 01821 (978) 667-3805, FAX (978) 663-9782
www.epotek.com

A Meridian Adhesives Group Company